



Printed Circuit Boards  
Interconnection Carriers

**PRINTED CIRCUIT BOARDS**

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**Schematic Key for Multilayer and HDI-Technology Build-Ups**

a	b	c	d	e	f	g + h + i
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04 243 FR4 70 L71.70 P18

columns and equal kind of positions are separated by "\_". Equal prefixes in one column are reduced to one.

04\_243\_FR4\_70\_L71.70\_p18

Layers	in $\mu$	Material	Build-Up	Assembly
Layer-1	70 $\mu$	Copper		A1
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-2	70 $\mu$	Copper	A1	B
	710 $\mu$	L-FR4		
Layer-3	70 $\mu$	Copper	A1	B
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
	180 $\mu$	Prepreg		
Layer-99	70 $\mu$	Copper	A1	B